Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

<table>
<thead>
<tr>
<th>HP Pavilion dv3 series</th>
</tr>
</thead>
<tbody>
<tr>
<td>Compaq CQ35 series</td>
</tr>
<tr>
<td>Name / Model #3</td>
</tr>
<tr>
<td>Name / Model #4</td>
</tr>
<tr>
<td>Name / Model #5</td>
</tr>
</tbody>
</table>

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface</td>
<td>With a surface greater than 10 sq cm Mother board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps,</td>
<td>0</td>
</tr>
<tr>
<td></td>
<td>switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td></td>
<td>LCD</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter</td>
<td></td>
<td></td>
</tr>
<tr>
<td>or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service</td>
<td></td>
</tr>
<tr>
<td>(gel/paste) and toner</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 screw driver</td>
<td>philip #1</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove battery module
2. Remove HDD & MINICARD door.
3. Remove HDD module
4. Remove expansion memory
5. Remove Mini-CARD & SIM board
6. Remove ODD assembly
7. Remove Keyboard
8. Remove strip cover (with power button PCB & Capacitive PCB)
9. Remove Speaker
10. Remove LCD cable and antenna
11. Divide LCD assembly from base assembly
12. Divide logic-up assembly(with TP module ) from base assembly
13. Divide M/B(with CPU and memory and thermal module) from base assembly
14. Remove thermal module • Fan assembly & RTC Battery from MB
15. Remove DC IN cable wire • USB board • system board • audio board and BT from logic-low assembly
16. Divide LCD cover & LCD bezel.
17. Divide LCD panel and Hinge Bracket.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Remove battery module
   Push the Battery Latch knob and remove the battery module

2. Remove HDD & MINICARD door.
   Divide the screw and remove those door
3. Remove HDD module
   Pull the hdd mylar to divide HDD module

4. Remove expansion memory
5. Remove Mini-CARD & SIM board
Divide the screw and remove minicard & SIM board

6. Remove ODD assembly
Divide the screw and remove ODD module
7. Remove Keyboard

Divide the screw 3 pcs and remove the Keyboard

1. Remove the screw of KB

2. Remove KB
8. Remove strip cover (with power button PCB & Capacitive PCB)
   1. Divide the screw 7 pcs

2. Remove the strip cover assy

2. Divide Strip cover

1. Divide capacitive board FFC from MB
3. Remove the screw then power board & capacitive board

9. Remove Speaker
   1. Remove the screw
2. Divide the speaker

10. Remove LCD cable and antenna
- Divide the antenna and LCD cable from routing area
11. Divide LCD assembly from base assembly
Divide the screws 2 pcs from Hinge base and divide it from base assembly
12. Divide logic-up assembly (with TP module) from base assembly

1. Divide the screws 13 pcs and divide it from base assembly

1. Divide 6 pcs screw from bottom side

2. Divide 7 pcs screw from top side
2. Divide FP module · TP on off board · TP btn board · caps lock board from logic up assy

3. Divide logic up assy from base assembly

1. Divide 7 pcs screw

2. Remove TP bracket & FP bracket
13. Divide M/B (with CPU and memory and thermal module) from base assembly

Divide the screws 2 pcs and divide it from base assembly
14. Remove thermal module & Fan assembly & RTC battery from MB

Divide the screws 2 pcs and divide it from MotherBoard

1. Divide the FAN screw from thermal module

2. Divide the thermal screw from MB

3. Divide the FAN module & thermal module from MB

Divide RTC Battery from MotherBoard
15. Remove DC IN cable wire, USB board, system board, audio board and BT from logic-low assembly.

Divide the screws 3 pcs and Remove DC IN cable wire, USB board, system board, audio board and BT from logic-low assembly.

16. Divide LCD cover & LCD bezel.
Divide the screws 2 pcs and Remove LCD bezel sub assy.
17. Divide LCD panel - Webcam - WWAN&WLAN Antenna module and Hinge Bracket.

Divide the screws 2pcs and divide it from LCD assembly.

2. Divide LCD Panel - Webcam module - WWAN&WLAN Antenna from LCD cover.

Divide the screws 6pcs and divide hinge from LCD assembly.

1. Divide the screw from LCD cover.

2. Divide the LCD hinge from LCD panel.